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**April 2015** 

# FGH60N60UFDTU\_F085 600V, 60A Field Stop IGBT

### **Features**

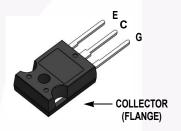
- · High Current Capability
- Low Saturation Voltage: V<sub>CE(sat)</sub> = 1.8 V @ I<sub>C</sub> = 60 A
- · High Input Impedance
- · Fast Switching
- RoHS Compliant
- · Qualified to Automotive Requirements of AEC-Q101

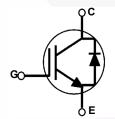
### **Applications**

- · Automotive chargers, Converters, High Voltage Auxiliaries
- · Inverters, PFC, UPS

## **General Description**

Using Novel Field Stop IGBT Technology, Fairchild's new series of Field Stop IGBTs offer the optimum performance for Automotive Chargers, Inverter, and other applications where low conduction and switching losses are essential.





# **Absolute Maximum Ratings**

Symbol	Description		Ratings	Unit
V <sub>CES</sub>	Collector to Emitter Voltage		600	V
V	Gate to Emitter Voltage		±20	V
$V_{GES}$	Transient Gate-to-Emitter Voltage		±30	V
	Collector Current	@ T <sub>C</sub> = 25°C	120	A
I <sub>C</sub>	Collector Current	@ T <sub>C</sub> = 100°C	60	A
I <sub>CM (1)</sub>	Pulsed Collector Current	@ T <sub>C</sub> = 25°C	180	A
	Maximum Power Dissipation	@ T <sub>C</sub> = 25°C	298	W
$P_{D}$	Maximum Power Dissipation	@ T <sub>C</sub> = 100°C	119	W
T <sub>J</sub>	Operating Junction Temperature		-55 to +150	°C
T <sub>stg</sub>	Storage Temperature Range		-55 to +150	°C
TL	Maximum Lead Temp. for soldering Purposes, 1/8" from case for 5 second	s	300	°C

#### Notes:

Repetitive test , Pulse width limited by max. junction temperature

### **Thermal Characteristics**

Symbol	Parameter	Тур.	Unit
$R_{\theta JC}(IGBT)$	Thermal Resistance, Junction to Case	0.33	°C/W
$R_{\theta JC}(Diode)$	Thermal Resistance, Junction to Case	1.1	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	40	°C/W

# **Package Marking and Ordering Information**

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FGH60N60UFDTU_F085	FGH60N60UFD	TO-247	Tube	N/A	N/A	30

# Electrical Characteristics of the IGBT $T_C = 25^{\circ}C$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
Off Charac	eteristics					
BV <sub>CES</sub>	Collector to Emitter Breakdown Voltage	$V_{GE} = 0 \text{ V}, I_{C} = 250 \mu A$	600	-	-	V
ΔBV <sub>CES</sub> / ΔT <sub>J</sub>	Temperature Coefficient of Breakdown Voltage	$V_{GE} = 0 \text{ V, } I_{C} = 250  \mu\text{A}$	-	0.67	-	V/°C
I <sub>CES</sub>	Collector Cut-Off Current	V <sub>CE</sub> = V <sub>CES</sub> , V <sub>GE</sub> = 0 V	-	-	250	μА
I <sub>GES</sub>	G-E Leakage Current	$V_{GE} = V_{GES}, V_{CE} = 0 V$	-	-	±400	nA
On Charac	teristics					
V <sub>GE(th)</sub>	G-E Threshold Voltage	I <sub>C</sub> = 250 μA, V <sub>CE</sub> = V <sub>GE</sub>	4.0	5.0	6.5	V
3=()		I <sub>C</sub> = 60 A, V <sub>GE</sub> = 15 V	-	1.8	2.9	V
V <sub>CE(sat)</sub>	Collector to Emitter Saturation Voltage	I <sub>C</sub> = 60 A, V <sub>GE</sub> = 15 V, T <sub>C</sub> = 125°C	-	2.1	-	V
Dynamic C	haracteristics					
C <sub>ies</sub>	Input Capacitance		-	2540	-	pF
C <sub>oes</sub>	Output Capacitance	$V_{CE} = 30 \text{ V}, V_{GE} = 0 \text{ V},$ f = 1  MHz	-	330	-	pF
C <sub>res</sub>	Reverse Transfer Capacitance	- 1 - 1 1011 12	-	110	-	pF
Switching	Characteristics					
t <sub>d(on)</sub>	Turn-On Delay Time		-	29	-	ns
t <sub>r</sub>	Rise Time		-	60	-	ns
t <sub>d(off)</sub>	Turn-Off Delay Time	$V_{CC} = 400 \text{ V}, I_{C} = 60 \text{ A},$ $R_{G} = 5 \Omega, V_{GE} = 15 \text{ V},$	-	138	-	ns
t <sub>f</sub>	Fall Time		-	28	80	ns
E <sub>on</sub>	Turn-On Switching Loss	Inductive Load, T <sub>C</sub> = 25°C	-	2.47	-	mJ
E <sub>off</sub>	Turn-Off Switching Loss		- /	0.81	-	mJ
E <sub>ts</sub>	Total Switching Loss		-/	3.28	-	mJ
t <sub>d(on)</sub>	Turn-On Delay Time		-	28	- /	ns
t <sub>r</sub>	Rise Time		-	55	- /	ns
t <sub>d(off)</sub>	Turn-Off Delay Time	V <sub>CC</sub> = 400 V, I <sub>C</sub> = 60 A,	-	147	-	ns
t <sub>f</sub>	Fall Time	$R_G = 5 \Omega$ , $V_{GE} = 15 V$ ,	-	71	-	ns
E <sub>on</sub>	Turn-On Switching Loss	Inductive Load, T <sub>C</sub> = 125°C	-	3.01	- //	mJ
E <sub>off</sub>	Turn-Off Switching Loss		-	1.21	- (	mJ
E <sub>ts</sub>	Total Switching Loss		-	4.22	- \	mJ
Qg	Total Gate Charge		-	192	-	nC
Q <sub>ge</sub>	Gate to Emitter Charge	$V_{CE} = 400 \text{ V}, I_{C} = 60 \text{ A},$	-	24	-	nC
Q <sub>gc</sub>	Gate to Collector Charge	V <sub>GE</sub> = 15 V	-	102	-	nC

# Electrical Characteristics of the Diode $T_C = 25^{\circ}C$ unless otherwise noted

Symbol	Parameter	Test Conditions		Min.	Тур.	Max	Units
V <sub>FM</sub> Diode Forward Voltage	Diode Forward Voltage	I <sub>E</sub> = 30 A	$T_{\rm C} = 25^{\rm o}{\rm C}$	-	1.70	2.6	V
	1F 00 //	T <sub>C</sub> = 125°C	-	1.54	-	] '	
t <sub>rr</sub>		I <sub>F</sub> = 30 A, di <sub>F</sub> /dt = 200 A/μs	$T_C = 25^{\circ}C$	ı	76	ı	ns
11			$T_{\rm C}$ = 125°C	-	242	-	
Q <sub>rr</sub>			$T_C = 25^{\circ}C$	1	208	ı	nC
11			$T_{\rm C}$ = 125 $^{\rm o}$ C	ı	1162	ı	

**Figure 1. Typical Output Characteristics** 

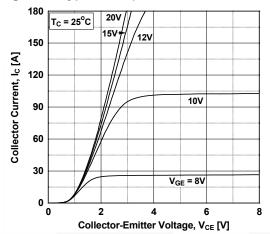


Figure 3. Typical Saturation Voltage Characteristics

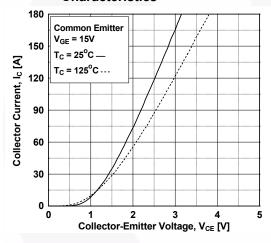
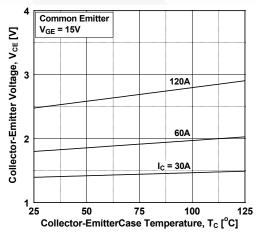


Figure 5. Saturation Voltage vs. Case
Temperature at Variant Current Level



**Figure 2. Typical Output Characteristics** 

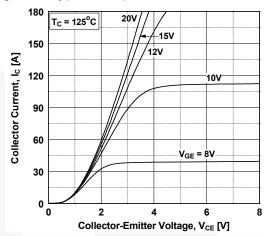


Figure 4. Transfer Characteristics

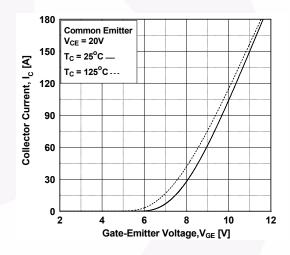


Figure 6. Saturation Voltage vs. V<sub>GE</sub>

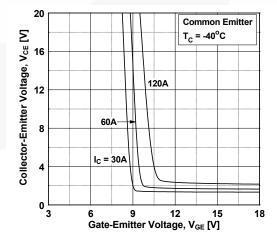


Figure 7. Saturation Voltage vs. V<sub>GE</sub>

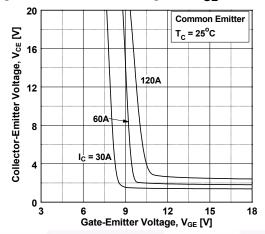


Figure 9. Capacitance Characteristics

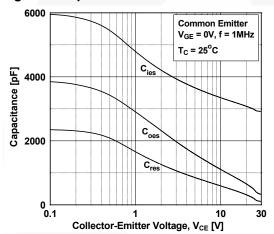


Figure 11. SOA Characteristics Characteristics

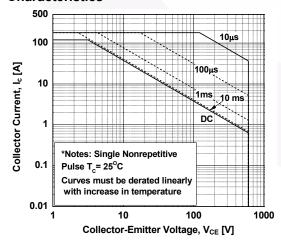


Figure 8. Saturation Voltage vs. V<sub>GE</sub>

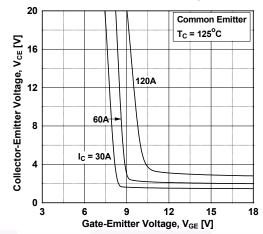


Figure 10. Gate charge Characteristics

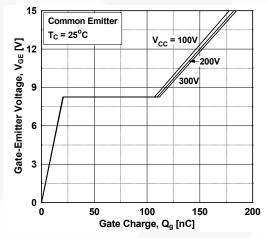


Figure 12. Turn off Switching SOA

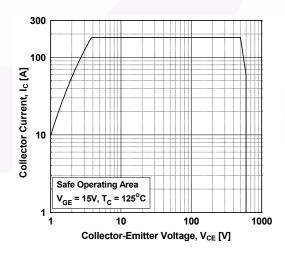


Figure 13. Turn-on Characteristics vs. Gate Resistance

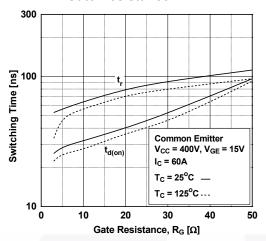


Figure 15. Turn-on Characteristics vs. Collector Current

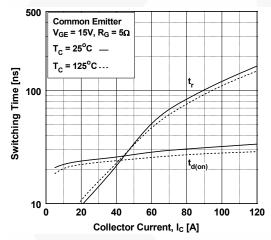


Figure 17. Switching Loss vs. Gate Resistance

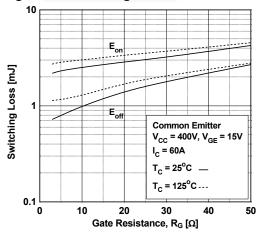


Figure 14. Turn-off Characteristics vs.
Gate Resistance

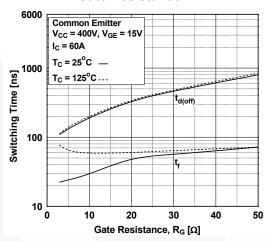


Figure 16. Turn-off Characteristics vs. Collector Current

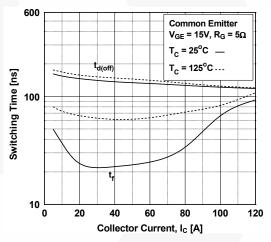


Figure 18. Switching Loss vs. Collector Current

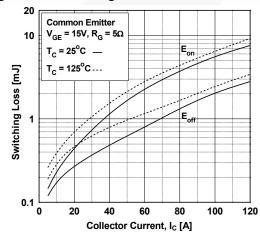


Figure 19. Forward Characteristics

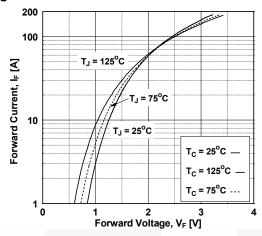


Figure 20. Reverse Current

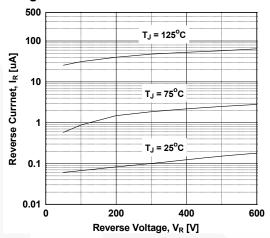


Figure 21. Stored Charge

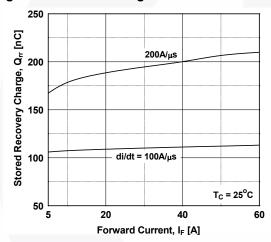


Figure 22. Reverse Recovery Time

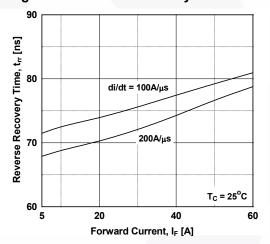
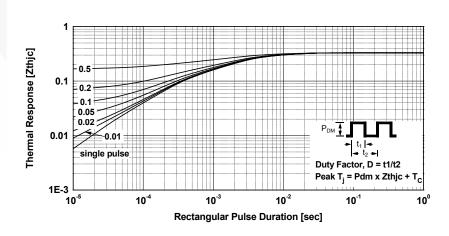
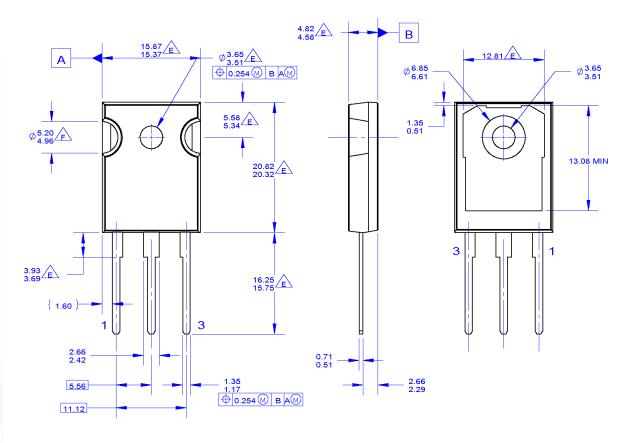


Figure 23. Transient Thermal Impedance of IGBT



### **Mechanical Dimensions**



NOTES: UNLESS OTHERWISE SPECIFIED.

- A. PACKAGE REFERENCE: JEDEC TO-247, ISSUE E, VARIATION AB, DATED JUNE, 2004.
- DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD
- FLASH, AND TIE BAR EXTRUSIONS.
  ALL DIMENSIONS ARE IN MILLIMETERS.
- DRAWING CONFORMS TO ASME Y14.5 1994
- DOES NOT COMPLY JEDEC STANDARD VALUE
- F NOTCH MAY BE SQUARE
- DRAWING FILENAME: MKT-TO247A03\_REV03

Figure 24. TO-247 3L - TO-247, MOLDED, 3 LEAD, JEDEC VARIATION AB

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Datasheet Identification Product Status		Definition		
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